



Advanced Solution for High Speed Direct Current Copper Pillar Technology

先进解决方案 高速直流 电镀铜柱技术

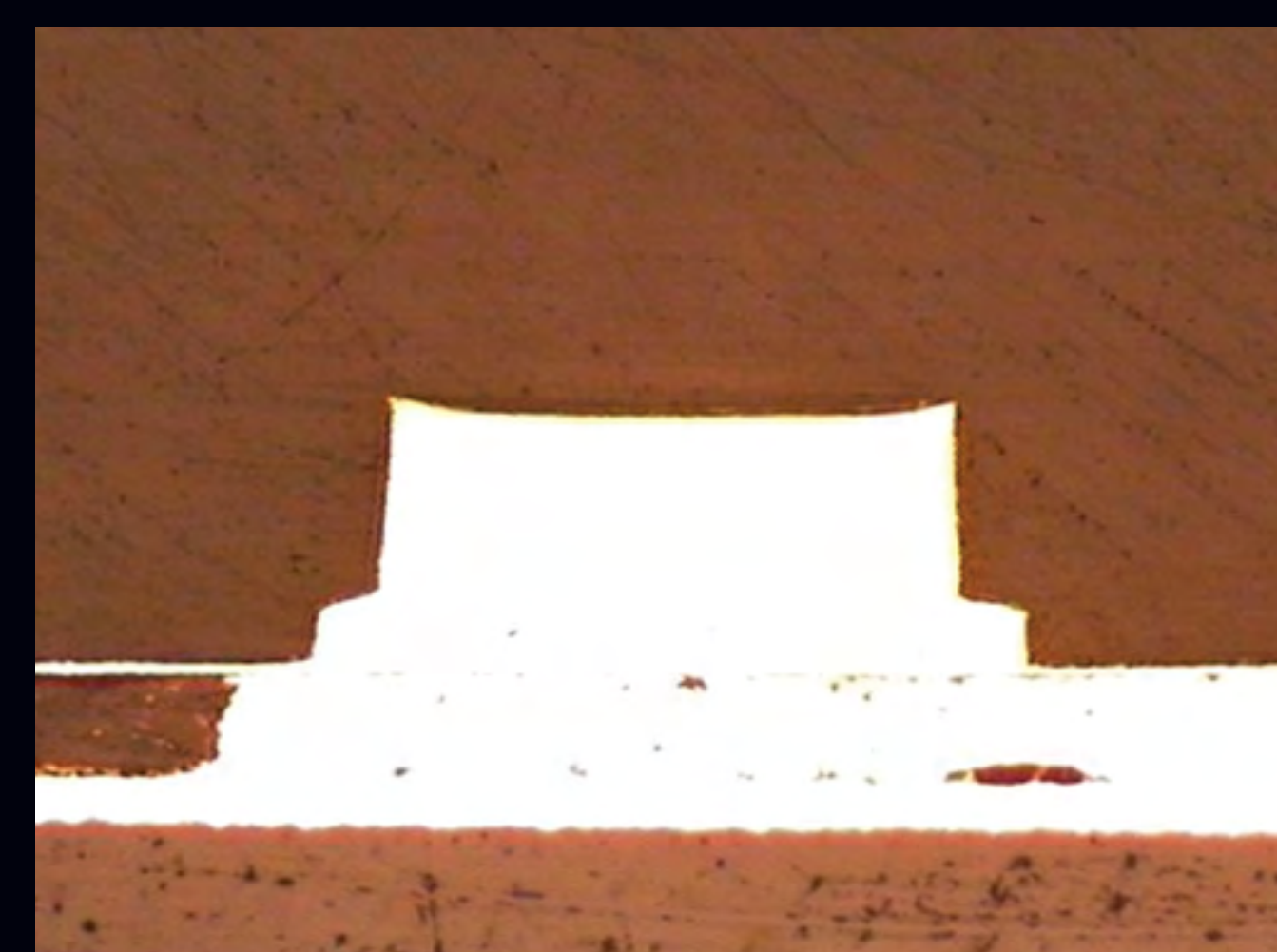
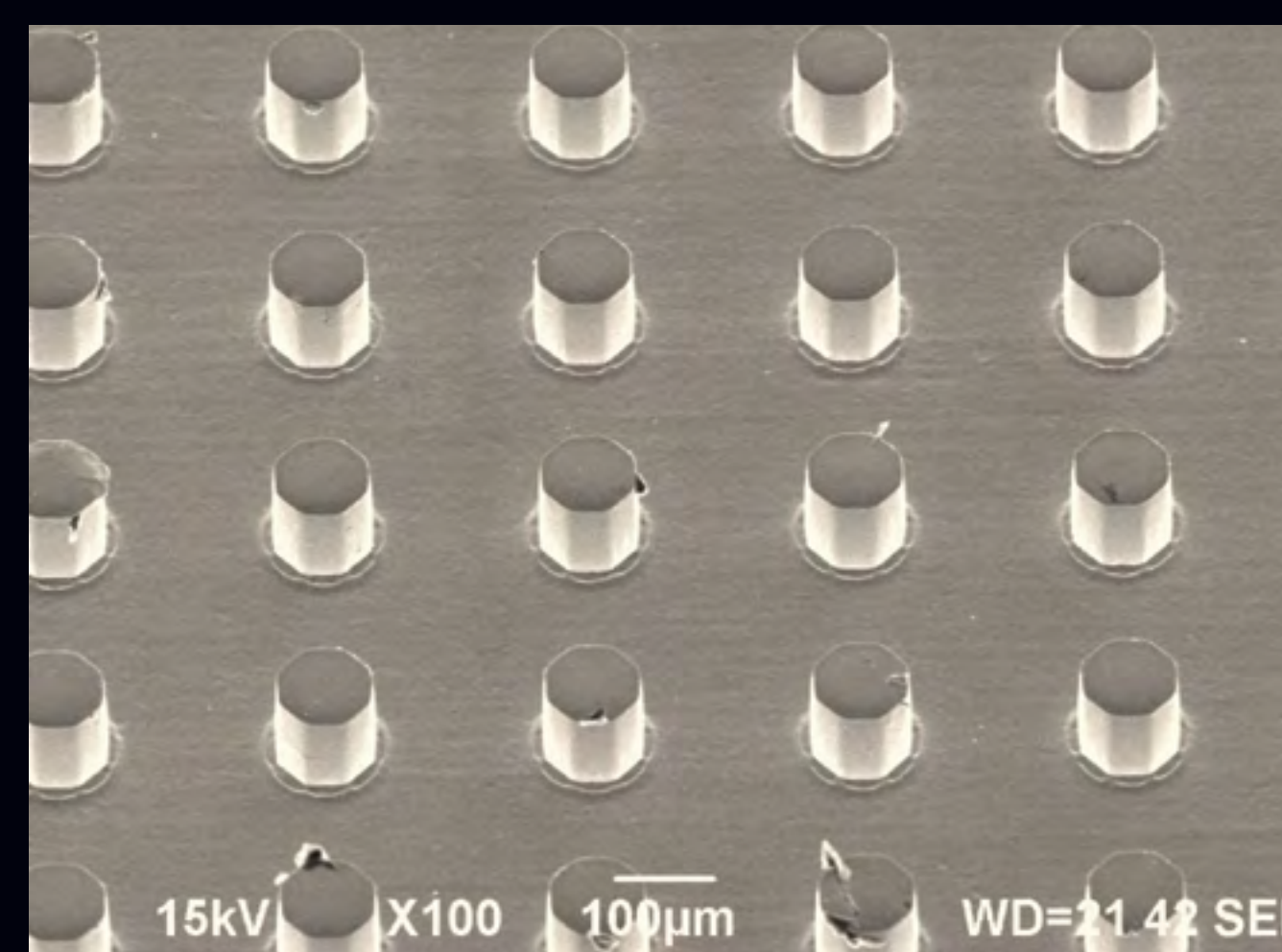
COPPER GLEAM™ CP360 Acid Copper COPPER GLEAM™ CP370 Acid Copper

COPPER GLEAM™ CP360 /CP370 Acid Copper is designed for copper pillar applications with high plating speed and excellent deposit uniformity. As a three-component system, COPPER GLEAM CP360 /CP370 is able to fine tune deposit morphology across a wide variety of Cu pillar feature sizes, while maintaining with-in unit and with-in panel uniformity and void free performance.

COPPER GLEAM™ CP360 /CP370 在铜柱电镀应用上展现快速电镀效率与优越的均匀性。三剂型药水的使用方式，可轻易透过参数微调达到不同客户需求，在兼顾unit和panel镀铜均匀性的同时，仍具备良好的镀铜品质。

Advantages 优点

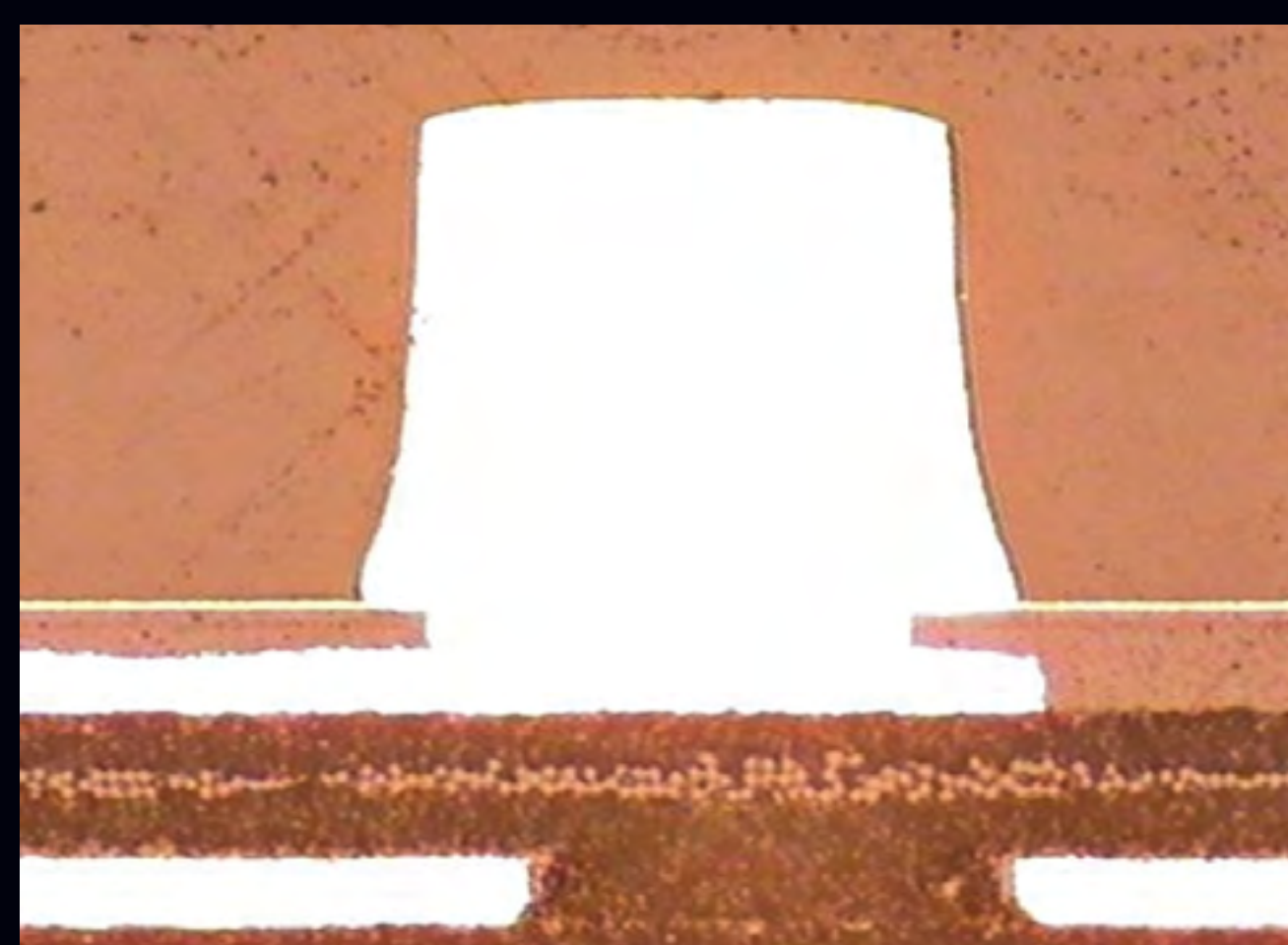
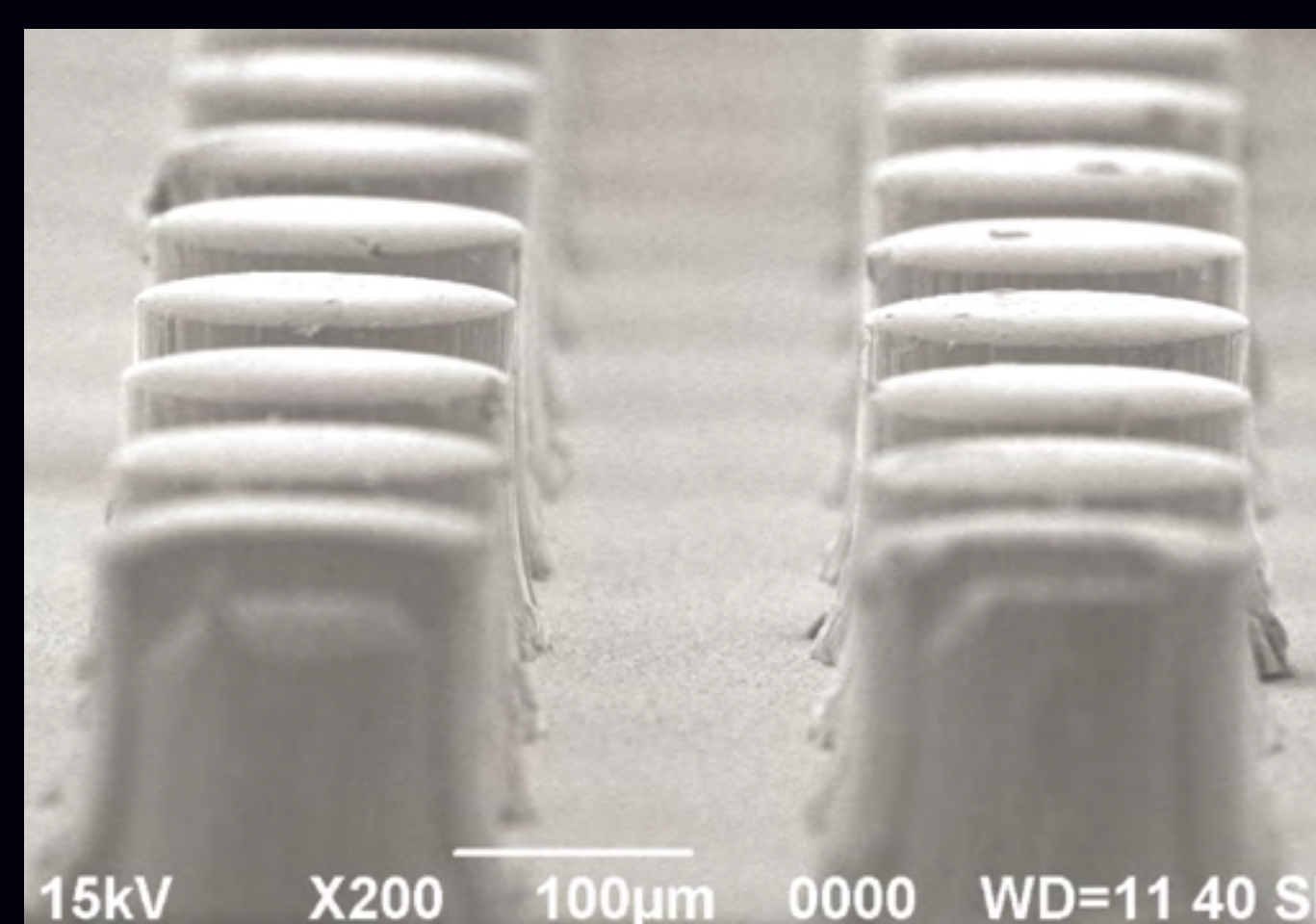
- Flat Pillar Top with Excellent Panel Uniformity
铜柱表面平整并有出色的全板面均匀性
- Can be Applied with Higher Current Density (13 ASD)
可搭配较高的操作电流 (13 ASD)
- Pure Deposition with Excellent Reliability Performance
高纯度铜沉积，优良可靠性表现
- Three Components Can be Analyzed by CVS
三种添加剂皆可用CVS分析



CP360 for pillar bump on flat panel

Dry Film open/height : 90/120um

Copper pillar height : 100um



CP370 for pillar bump on dent via

Dry film open/height : 170/150um

Copper pillar height : 140um

